

FAST RECOVERY DIODE

TOSHIBA (DISCRETE/OPTO)

39 DE 9097250 0002242 9

1S2711 1500V 1.5A

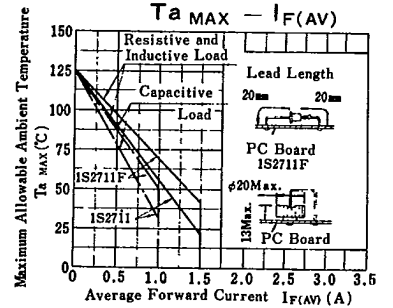
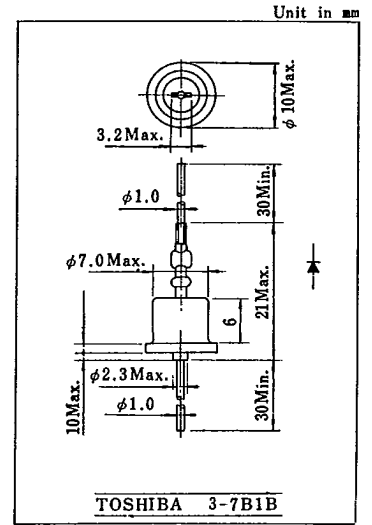
MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	V_{RRM}	1500	V
Non-Repetitive Peak Reverse Voltage	V_{RSM}	1600	V
Average Forward Current ($T_a=20^\circ\text{C}$)	$I_{F(AV)}$	1.5	A
Peak One Cycle Surge Forward Current (Non-Repetitive)	I_{FSM}	60(50Hz)	A
Junction Temperature	T_j	-40~125	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-40~150	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Peak Forward Voltage	V_{FM}	$I_{FM}=2.0\text{A}, T_j=25^\circ\text{C}$	-	-	1.2	V
Repetitive Peak Reverse Current	$I_{RRM} (1)$	$V_{RRM}=\text{Rated}, T_j=25^\circ\text{C}$	-	-	10	μA
	$I_{RRM} (2)$	$V_{RRM}=\text{Rated}, T_j=125^\circ\text{C}$	-	-	600	
Reverse Recovery Time	t_{rr}	$I_F=20\text{mA}, I_R=1\text{mA}, T_j=25^\circ\text{C}$	-	-	20	μs
Forward Recovery Voltage	V_{fr}	$I_F=0.1\text{A}, t_r=100\text{ns}, t_p=5\mu\text{s}, T_j=25^\circ\text{C}$	-	-	5	V

- Notes : 1. Soldering : 5mm is the minimum to be kept between case and soldering part.
 2. Lead Bending : 5mm is the minimum to be kept from the case when bend the lead wire.



3JH61 600V 3A

MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	3BH61	100	V
	3DH61	200	
	3GH61	400	
	3JH61	600	
Average Forward Current	$I_{F(AV)}$	1.5 * 1	A
		3.0 * 2	
Peak One Cycle Surge Forward Current (Non-Repetitive)	I_{FSM}	60(50Hz)	A
Junction Temperature	T_j	-40~150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-40~150	$^\circ\text{C}$

- * 1 No Heat Sink * 2 With Heat Sink

ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Peak Forward Voltage	V_{FM}	$I_{FM}=3\text{A}, T_j=25^\circ\text{C}$	-	-	1.4	V
Repetitive Peak Reverse Current	$I_{RRM} (1)$	$V_{RRM}=\text{Rated}, T_j=25^\circ\text{C}$	-	-	20	μA
	$I_{RRM} (2)$	$V_{RRM}=\text{Rated}, T_j=150^\circ\text{C}$	-	-	3000	
Reverse Recovery Time	$t_{rr} (1)$	$I_F=20\text{mA}, I_R=1\text{mA}, T_j=25^\circ\text{C}$	-	-	1.5	μs
	$t_{rr} (2)$	$I_F=20\text{mA}, I_R=20\text{mA}, T_j=25^\circ\text{C}$	-	-	0.5	
Forward Recovery Voltage	V_{fr}	$I_F=0.1\text{A}, t_p=5\mu\text{s}, T_j=25^\circ\text{C}$	-	-	10	V

- Notes : 1. Soldering : 5mm is the minimum to be kept between case and soldering part.
 2. Lead Bending : 5mm is the minimum to be kept from the case when bend the lead wire.

